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PATENT ABSTRACTS OF JAPAN

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(71) Applicant: SUMITOMO METAL MINING CO

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(74) Representative:

(54) HERMETIC SEAL COVER AND ITS MANUFACTURE

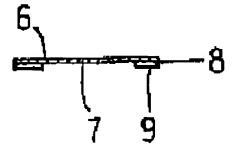
(57) Abstract:

PROBLEM TO BE SOLVED: To implement a highly reliable hermetic seal by providing a brazing filler metal layer on a gold-planting layer on a member of a desired shape, a metal layer which has a predetermined thickness and is hard to oxidize on the brazing filler metal layer, and eliminating an oxide form the interface between the brazing filler metal layer.

SOLUTION: A seal cover 6 is manufactured by forming a gold-plating layer 7 on the surface of a ceramic member by barrel planting, and then by forming a gold-tin alloy prazing filler metal layer 8 while ponding the alloy by thermocompression in desired positions on one surface of the layer 7. Then, an oxide film on the gold-tin prazing filler metal surface is temoved in a pre-plating process step, and a gold-plating film 9 whose thickness range from 0.01 to 1.0 μm is formed on the gold-tin brazing

filler metal surface using a commercially available gold plating solution. The seal cover 6 for nemetically sealing an object has a metal-plating film that is hard to oxidize, i.e., the film 9 formed on the surface from which the oxide film of the brazing filler metal member has been removed. Therefore, no voids are produced when the object is nermetically sealed, and thus the object can be sealed reliably.

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Title:

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Country:

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Α

Inventor(s):

MORI NOBUMOTO

Applicant/Assignee: Inquire Regarding Licensing

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JP1997000353173

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Priority Number(s):

Dec. 22, 1997 JP19971997353173

Abstract:

Problem to be solved: To implement a highly reliable hermetic seal by providing a brazing filler metal layer on a gold-planting layer on a member of a desired shape, a metal layer which has a predetermined thickness and is hard to oxidize on the brazing filler metal layer, and eliminating an oxide form the interface between the brazing filler metal layer and the metal layer.



Solution: A seal cover 6 is manufactured by forming a gold-plating laver 7 on the surface of a ceramic member by barrel planting, and then by forming a gold-tin alloy brazing filler metal layer 8 while bonding the alloy by thermocompression in desired positions on one surface of the layer 7. Then, an oxide film on the gold-tin brazing filler metal surface is removed in a pre-plating process step, and a gold-plating film 9 whose thickness range from 0.01 to 1.0 µm is formed on the gold-tin brazing filler metal surface using a commercially available gold plating solution. The seal cover 6 for hemetically sealing an object has a metal-plating film that is hard to oxidize, i.e., the film 9 formed on the surface from which the oxide film of the brazing filler metal member has been removed. Therefore, no voids are produced when the object is hermetically

sealed, and thus the object can be sealed reliably.

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